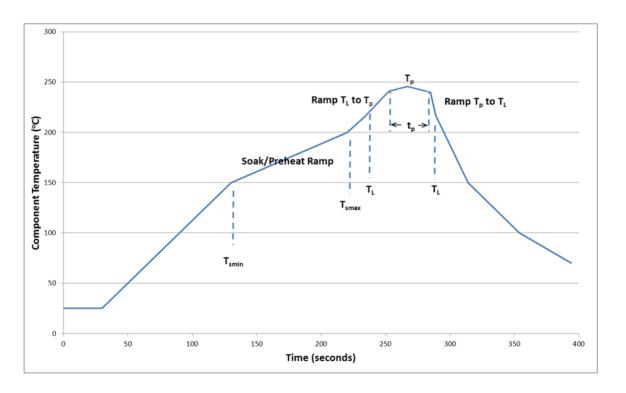


## **Surface Mount Solder Reflow Profile - PTVS Overvoltage Protectors**

Surface Mount Packages are qualified by simulating the solder reflow conditions specified in IPC/JEDEC J-STD-020, which defines soldering conditions for moisture reflow sensitivity classification.

Users should ensure they do not exceed the scope of IPC/JEDEC J-STD-020 (Pb-Free) during solder assembly.

Profile Feature	Profile Limits
Preheat temperature min. (T <sub>smin</sub> )	150 °C
Preheat temperature max. (T <sub>smax</sub> )	200 °C
Ramp time (T <sub>smax -</sub> T <sub>smin)</sub>	60 – 120 seconds
Ramp –up rate ( T <sub>L</sub> to T <sub>p</sub> )	3 °C/second max.
Liquidus temperature (T <sub>L</sub> )	217 °C
Time maintained above T <sub>L</sub>	60 – 150 seconds
Peak package body temperature	260 °C
Time within 5 °C of peak temperature (t <sub>p</sub> )	30 seconds max.
Ramp –down rate ( T <sub>p</sub> to T <sub>L</sub> )	6 °C/second max.
Time from 25 °C to peak temperature	8 minutes max.



www.bourns.com Oct 2015